

## N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY			
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (mΩ)(Typ.)	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)
60	75 at V <sub>GS</sub> = 10 V	3.0	7.5 nC
	86 at V <sub>GS</sub> = 4.5 V	2.1	

### FEATURES

- DT-Trench Power MOSFET
- 100 % Rg and UIS Tested

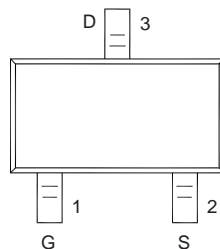


RoHS  
COMPLIANT

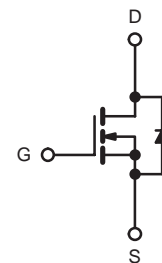
### APPLICATIONS

- Battery Switch
- DC/DC Converter

(SOT-23-3L)



Top View



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T <sub>A</sub> = 25 °C, unless otherwise noted			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	60	V
Gate-Source Voltage	V <sub>GS</sub>	± 20	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	I <sub>D</sub>	T <sub>C</sub> = 25 °C	3.0
		T <sub>C</sub> = 70 °C	1.8
		T <sub>A</sub> = 25 °C	2.1 <sup>b, c</sup>
		T <sub>A</sub> = 70 °C	1.5 <sup>b, c</sup>
Pulsed Drain Current	I <sub>DM</sub>	9	A
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	
		T <sub>A</sub> = 25 °C	0.91 <sup>b, c</sup>
Avalanche Current	I <sub>AS</sub>	6	mJ
Single-Pulse Avalanche Energy	E <sub>AS</sub>	1.8	
Maximum Power Dissipation	P <sub>D</sub>	T <sub>C</sub> = 25 °C	1.66
		T <sub>C</sub> = 70 °C	1.06
		T <sub>A</sub> = 25 °C	1.09 <sup>b, c</sup>
		T <sub>A</sub> = 70 °C	0.7 <sup>b, c</sup>
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 5 s	R <sub>thJA</sub>	90	115	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJC</sub>	60	75	

Notes:

- Based on T<sub>C</sub> = 25 °C.
- Surface Mounted on 1" x 1" FR4 board.
- t = 5 s.
- Maximum under Steady State conditions is 120 °C/W.

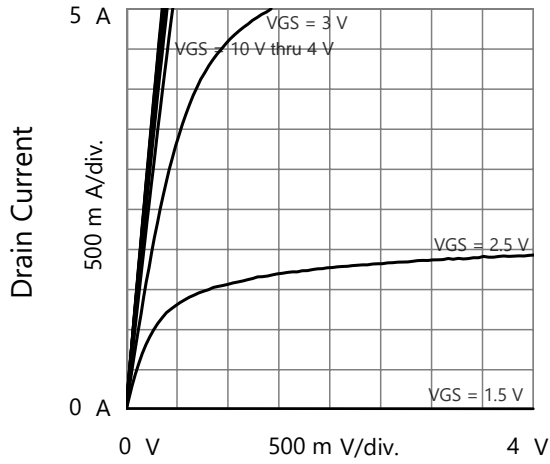
<b>MOSFET SPECIFICATIONS</b> $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{DS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	60			V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$		55		mV/ $^\circ\text{C}$
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			-5		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	1.0		3.0	
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}$			1.0	$\mu\text{A}$
		$V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$			10	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$	8.0			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 1.9\text{ A}$		75	90	m $\Omega$
		$V_{GS} = 4.5\text{ V}, I_D = 1.7\text{ A}$		86	103	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 15\text{ V}, I_D = 1.9\text{ A}$		5		S
<b>Dynamic<sup>b</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$		271		$\mu\text{F}$
Output Capacitance	$C_{oss}$			21		
Reverse Transfer Capacitance	$C_{rss}$			17		
Total Gate Charge	$Q_g$	$V_{DS} = 30\text{ V}, V_{GS} = 10\text{ V}, I_D = 1.9\text{ A}$		7.5		nC
Gate-Source Charge	$Q_{gs}$			0.5		
Gate-Drain Charge	$Q_{gd}$			1.7		
Gate Resistance	$R_g$	$f = 1\text{ MHz}$		2.5		$\Omega$
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 30\text{ V}, R_L = 20\text{ }\Omega$ $I_D \cong 1.9\text{ A}, V_{GEN} = 10\text{ V}, R_G = 1\text{ }\Omega$		4	6	ns
Rise Time	$t_r$			10	15	
Turn-Off Delay Time	$t_{d(off)}$			10	15	
Fall Time	$t_f$			7	10.5	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 30\text{ V}, R_L = 20\text{ }\Omega$ $I_D = 1.9\text{ A}, V_{GEN} = 4.5\text{ V}, R_G = 1\text{ }\Omega$		15	23	ns
Rise Time	$t_r$			16	24	
Turn-Off Delay Time	$t_{d(off)}$			11	17	
Fall Time	$t_f$			11	17	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	$T_C = 25\text{ }^\circ\text{C}$			3.0	A
Pulse Diode Forward Current <sup>a</sup>	$I_{SM}$				9.0	
Body Diode Voltage	$V_{SD}$	$I_S = 1\text{ A}$		0.6	1.2	V
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 1.9\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$		15	23	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$			10	15	nC
Reverse Recovery Fall Time	$t_a$			12		ns
Reverse Recovery Rise Time	$t_b$			3		

Notes:

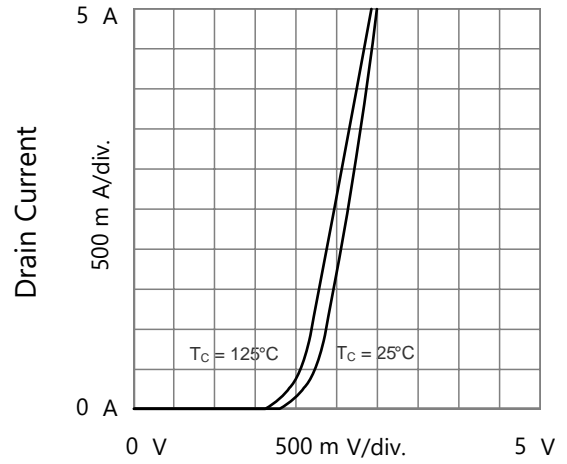
- Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

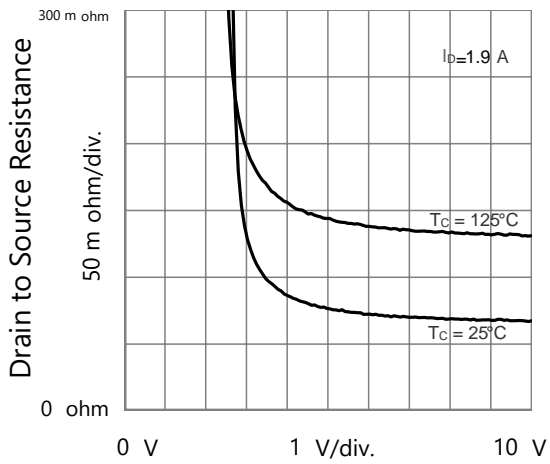
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



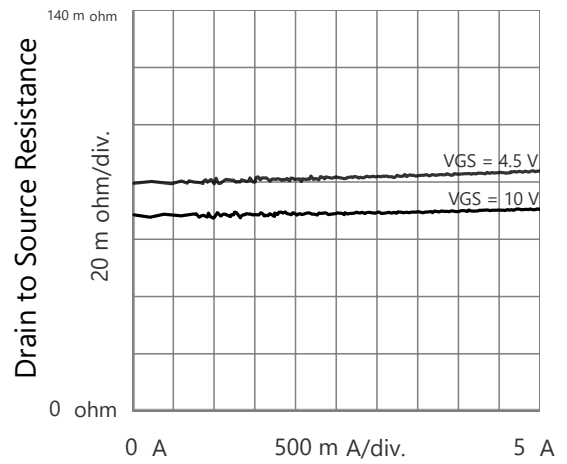
Drain to Source Voltage  
Output Characteristics



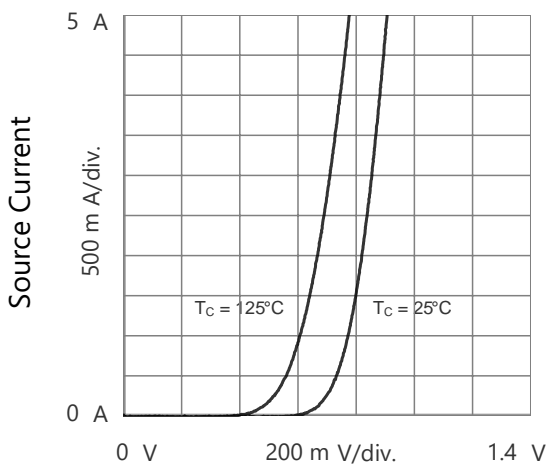
Gate to Source Voltage  
Transfer Characteristics



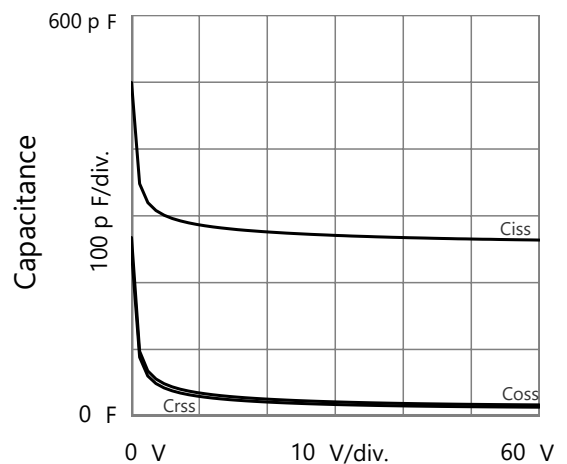
Gate to Source Voltage  
Drain to Source Resistance vs. Gate to Source Voltage



Drain Current  
Drain to Source Resistance vs. Drain Current

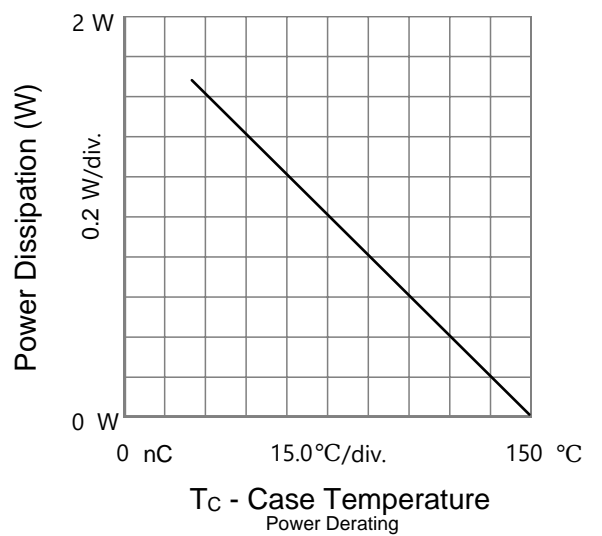
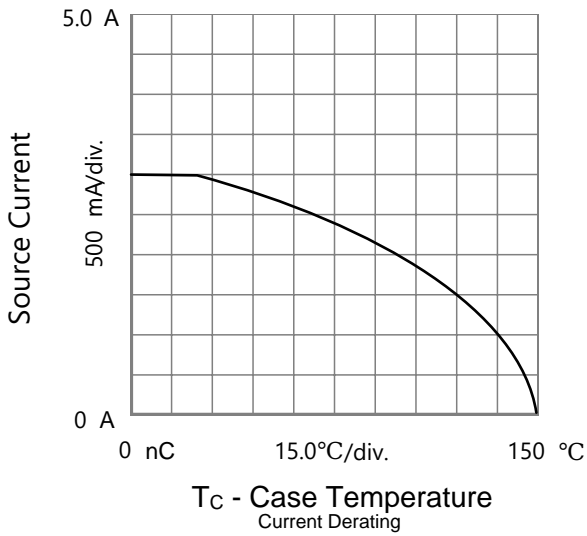
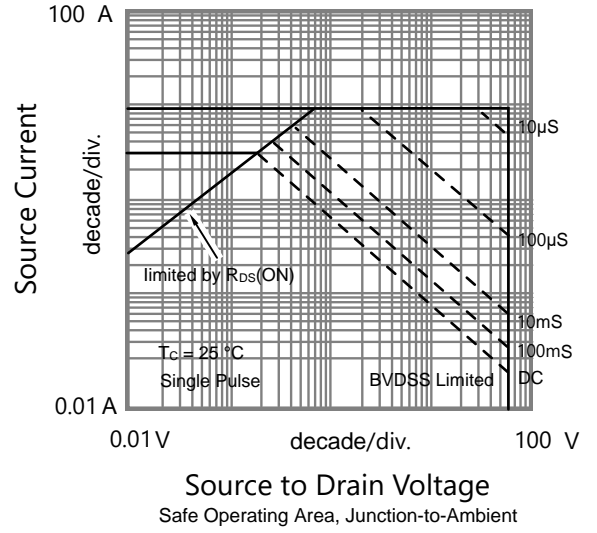
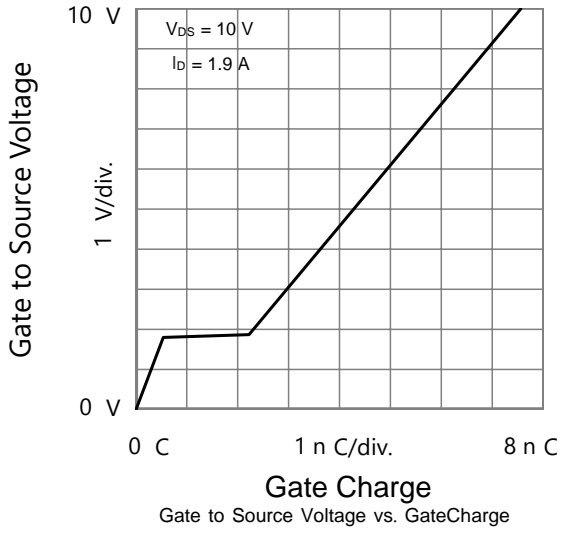


Source to Drain Voltage  
Body Diode Forward Characteristics

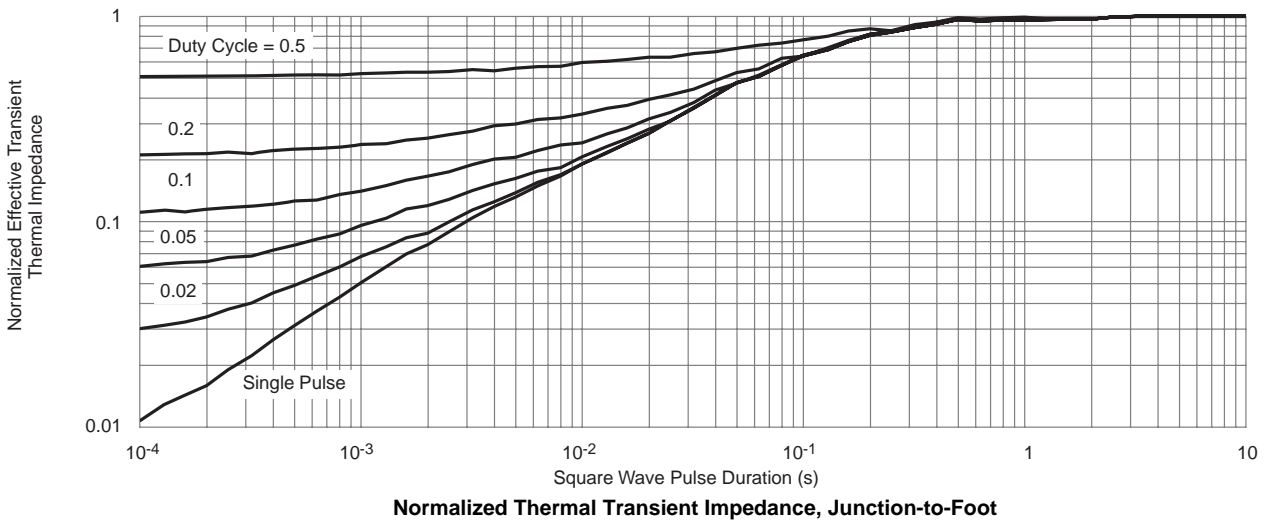
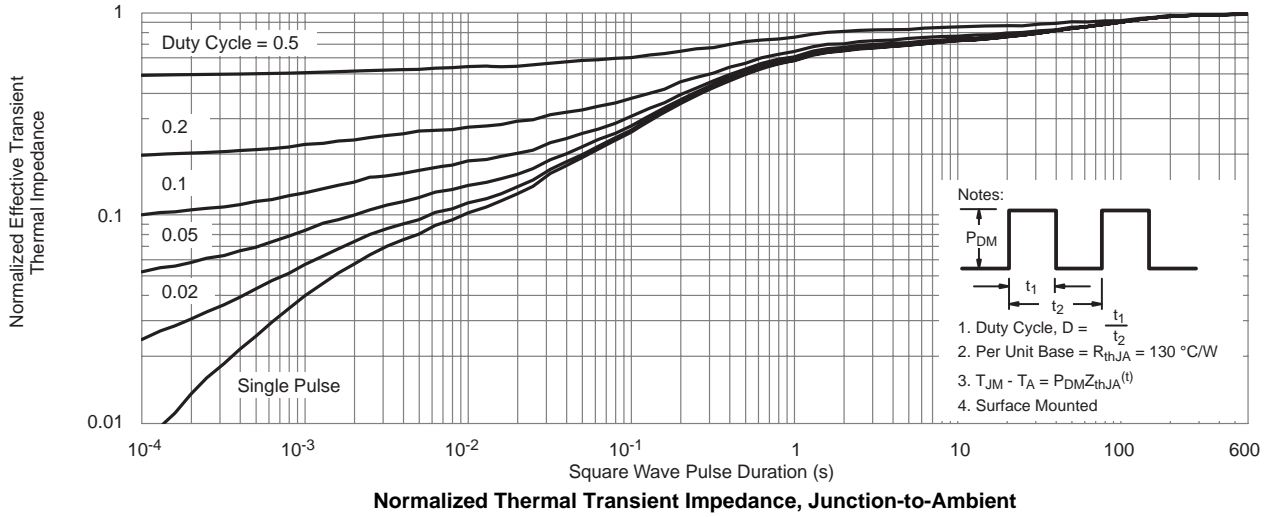


Drain to Source Voltage  
Capacitances

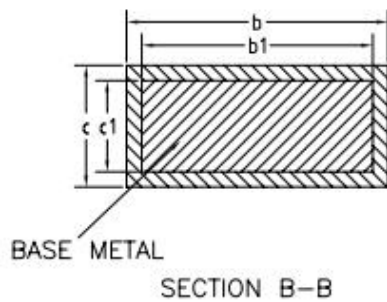
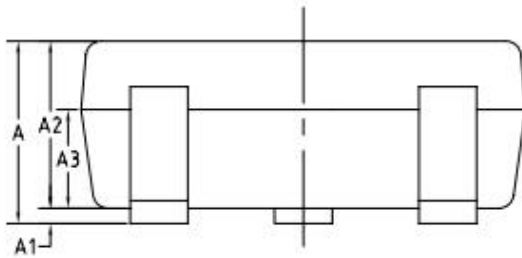
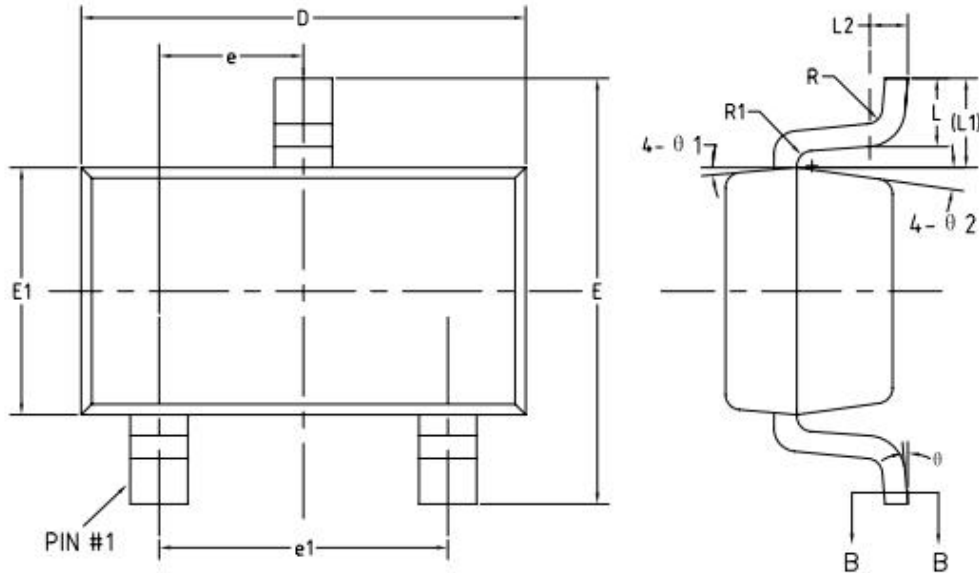
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



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SOT-23-3L PACKAGE OUTLINE



COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX
A	-	-	1.50
A1	0.00	-	0.18
A2	0.85	1.10	1.35
A3	0.58	0.65	0.72
b	0.23	-	0.53
b1	0.20	0.40	0.50
c	0.09	-	0.22
c1	0.08	0.13	0.21
D	2.78	2.95	3.10
E	2.58	2.80	3.03
E1	1.55	1.65	1.78
e	0.83	0.95	1.07
e1	1.78	1.90	2.02
L	0.28	0.45	0.62
L1	0.59REF		
L2	0.25BSC		
R	0.04	-	-
R1	0.04	-	0.21
θ	0°	-	8°
θ 1	8°	10°	12°
θ 2	8°	10°	12°

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